# **MA2S101**

# Silicon epitaxial planar type

### For switching circuits

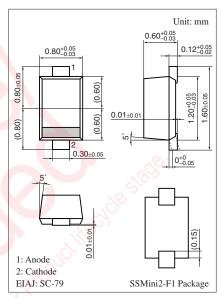
#### ■ Features

- High breakdown voltage:  $V_R = 250 \text{ V}$
- Small terminal capacitance C<sub>t</sub>
- Suitable for high-density mounting

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	250	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	250	V
Forward current	$I_{\mathrm{F}}$	100	mA
Peak forward current	$I_{FM}$	225	mA
Non-repetitive peak forward	I <sub>FSM</sub>	500	mA
surge current *			
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C





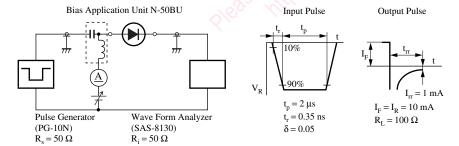
Marking Symbol: 1P

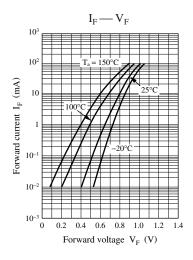
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

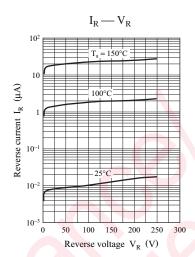
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	$I_F = 70 \text{ mA}$	90	950	1.2	V
Reverse current	$I_R$	$V_R = 250 \text{ V}$	00/		1.0	μΑ
Terminal capacitance	$C_{t}$	$V_R = 0 V, f = 1 MHz$	0.7		3.0	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 10 \text{ mA}$			60	ns
		$I_{rr} = 1 \text{ mA}$ , $R_L = 100 \Omega$				

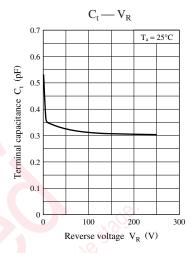
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 20 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit









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